



74LVX125

Low Voltage Quad Buffer with 3-STATE Outputs

Features

- Input voltage level translation from 5V to 3V
- Ideal for low power/low noise 3.3V applications
- Guaranteed simultaneous switching noise level and dynamic threshold performance

General Description

The LVX125 contains four independent non-inverting buffers with 3-STATE outputs. The inputs tolerate voltages up to 7V allowing the interface of 5V systems to 3V systems.

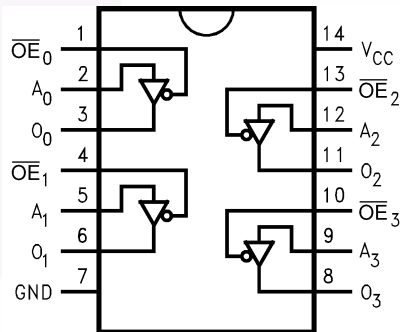
Ordering Information

Order Number	Package Number	Package Description
74LVX125M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LVX125SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVX125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

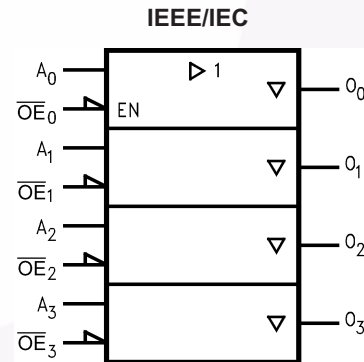
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Logic Symbol



Pin Description

Pin Names	Description
A_n	Inputs
\overline{OE}_n	Output Enable Inputs
O_n	Outputs

Truth Table

Inputs		Output
\overline{OE}_n	A_n	O_n
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
Z = High Impedance
X = Immaterial

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	-0.5V to +7.0V
I_{IK}	DC Input Diode Current, $V_I = -0.5V$	-20mA
V_I	DC Input Voltage	-0.5V to 7V
I_{OK}	DC Output Diode Current $V_O = -0.5V$	-20mA
	$V_O = V_{CC} + 0.5V$	+20mA
V_O	DC Output Voltage	-0.5V to $V_{CC} + 0.5V$
I_O	DC Output Source or Sink Current	$\pm 25mA$
I_{CC} or I_{GND}	DC V_{CC} or Ground Current	$\pm 50mA$
T_{STG}	Storage Temperature	-65°C to +150°C
P	Power Dissipation	180mW

Recommended Operating Conditions⁽¹⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	2.0V to 3.6V
V_I	Input Voltage	0V to 5.5V
V_O	Output Voltage	0V to V_{CC}
T_A	Operating Temperature	-40°C to +85°C
$\Delta t / \Delta V$	Input Rise and Fall Time	0ns/V to 100ns/V

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V _{CC}	Conditions	T _A = +25°C			T _A = -40°C to +85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
V _{IH}	HIGH Level Input Voltage	2.0		1.5			1.5		V
		3.0		2.0			2.0		
		3.6		2.4			2.4		
V _{IL}	LOW Level Input Voltage	2.0				0.5		0.5	V
		3.0				0.8		0.8	
		3.6				0.8		0.8	
V _{OH}	HIGH Level Output Voltage	2.0	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -50μA	1.9	2.0		1.9		V
		3.0	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -50μA	2.9	3.0		2.9		
			V _{IN} = V _{IL} or V _{IH} , I _{OH} = -4mA	2.58			2.48		
V _{OL}	LOW Level Output Voltage	2.0	V _{IN} = V _{IL} or V _{IH} , I _{OL} = 50μA		0.0	0.1		0.1	V
		3.0	V _{IN} = V _{IL} or V _{IH} , I _{OL} = 50μA		0.0	0.1		0.1	
			V _{IN} = V _{IL} or V _{IH} , I _{OL} = 4mA			0.36		0.44	
I _{OZ}	3-STATE Output Off-State Current	3.6	V _{IN} = V _{IL} or V _{IH} , V _{OUT} = V _{CC} or GND			±0.25		±2.5	μA
I _{IN}	Input Leakage Current	3.6	V _{IN} = 5.5V or GND			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	3.6	V _{IN} = V _{CC} or GND			4.0		40.0	μA

Noise Characteristics⁽²⁾

Symbol	Parameter	V _{CC} (V)	C _L (pF)	T _A = 25°C		Units
				Typ.	Limit	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	50	0.3	0.8	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	50	-0.3	-0.8	V
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	3.3	50		2.0	V
V _{ILD}	Maximum LOW Level Dynamic Input Voltage	3.3	50		0.8	V

Note:

2. Input t_r = t_f = 3ns

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C			T _A = -40°C to +85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
t _{PLH} , t _{PHL}	Propagation Delay Time, Data to Output	2.7	C _L = 15pF		5.8	10.1	1.0	13.5	ns
			C _L = 50pF		8.3	13.6	1.0	17.0	
		3.3 ± 0.3	C _L = 15pF		4.4	6.2	1.0	8.5	
			C _L = 50pF		6.9	9.7	1.0	12.0	
t _{PZH} , t _{PZL}	Output Enable Time	2.7	C _L = 15pF, R _L = 1kΩ		5.3	9.3	1.0	12.5	ns
			C _L = 50pF, R _L = 1kΩ		7.8	12.8	1.0	16.0	
		3.3 ± 0.3	C _L = 15pF, R _L = 1kΩ		4.0	5.6	1.0	7.5	
			C _L = 50pF, R _L = 1kΩ		6.5	9.1	1.0	11.0	
t _{PHZ} , t _{PLZ}	Output Disable Time	2.7	C _L = 50pF, R _L = 1kΩ		10.0	15.7	1.0	19.0	ns
		3.3 ± 0.3	C _L = 50pF, R _L = 1kΩ		8.3	11.2	1.0	13.0	
t _{OSHL} , t _{OSLH}	Output to Output Skew ⁽³⁾	2.7	C _L = 50pF			1.5		1.5	ns
		3.3				1.5		1.5	

Note:

3. Parameter guaranteed by design $t_{OSLH} = |t_{PLHm} - t_{PLHn}|$, $t_{OSHL} = |t_{PHLm} - t_{PHLn}|$

Capacitance

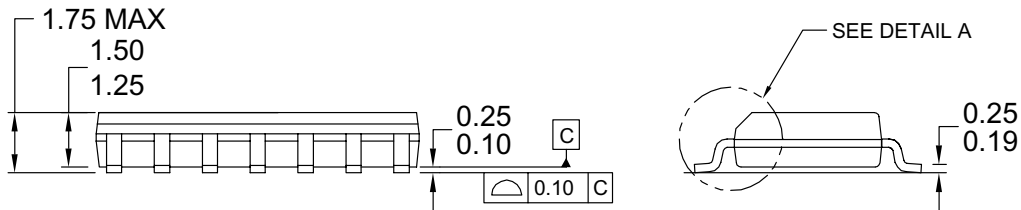
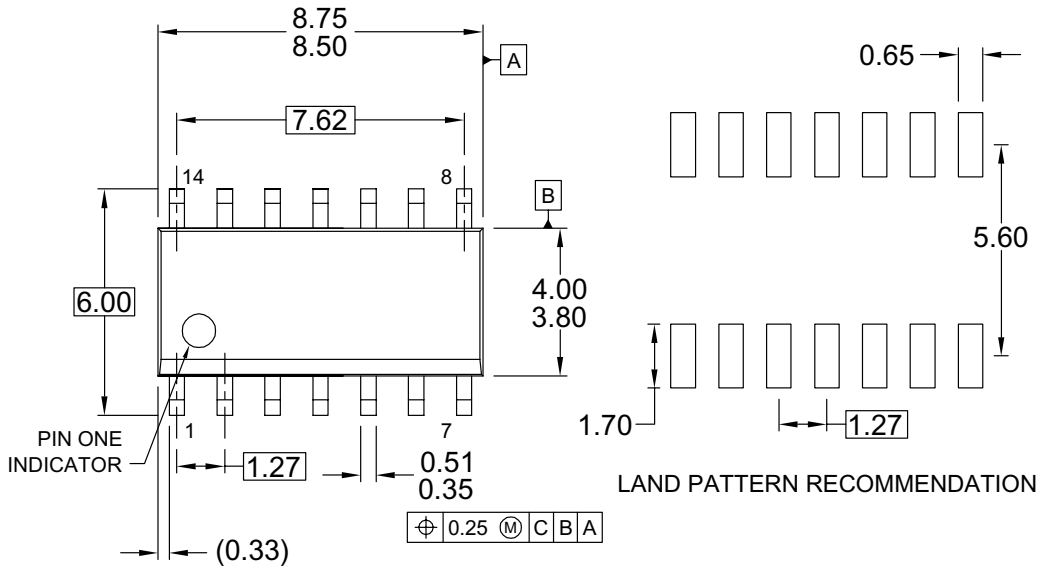
Symbol	Parameter	T _A = +25°C			T _A = -40°C to +85°C		Units
		Min.	Typ.	Max.	Min.	Max.	
C _{IN}	Input Capacitance		4	10		10	pF
C _{PD}	Power Dissipation Capacitance ⁽⁴⁾		14				pF

Note:

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation: $I_{CC(opr.)} = \frac{C_{PD} \times V_{CC} \times f_{IN} \times I_{CC}}{4 \text{ (per bit)}}$

Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

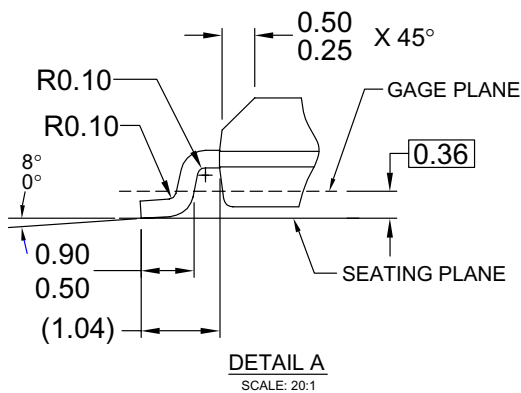


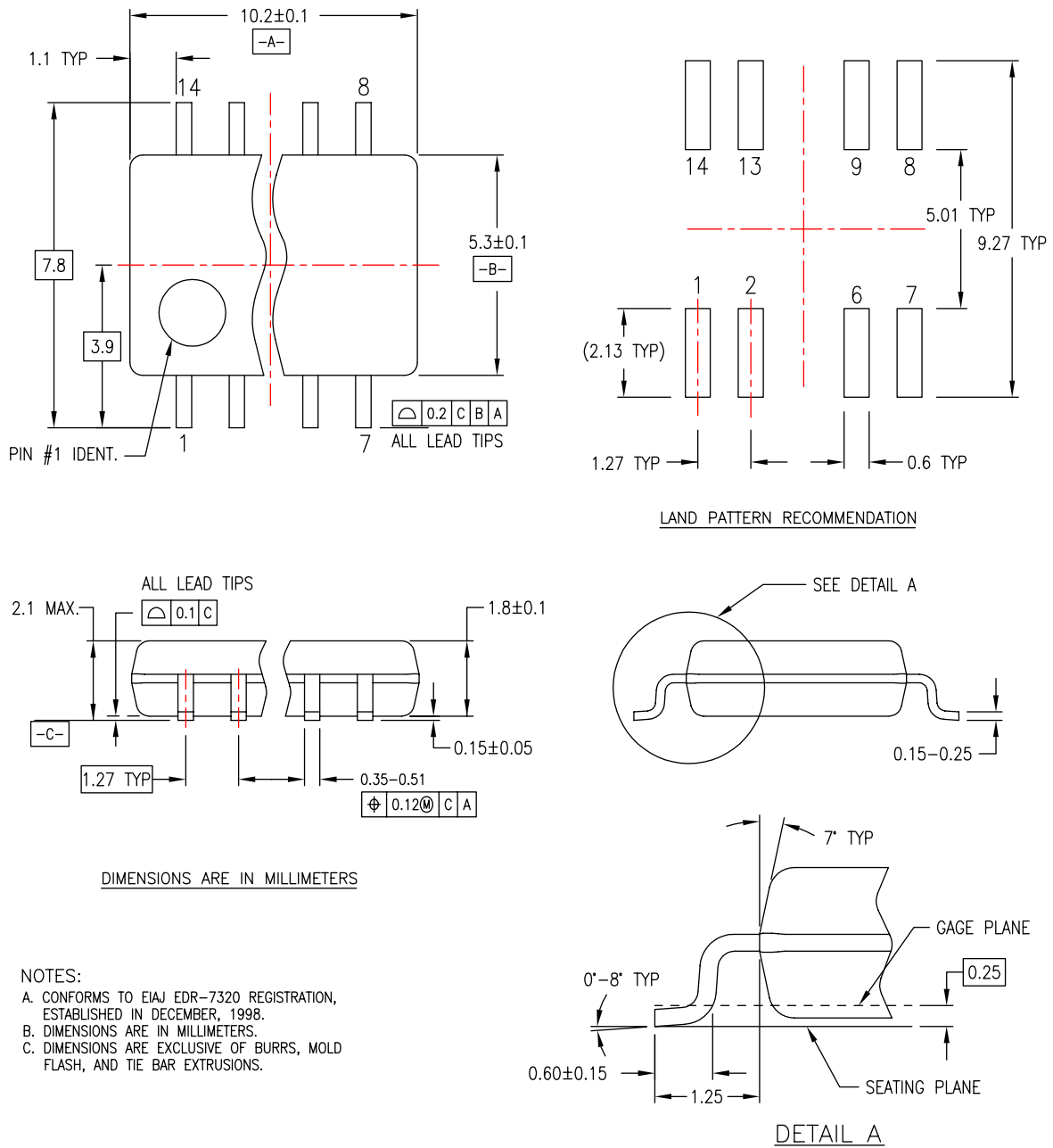
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Physical Dimensions (Continued)



M14DREVC

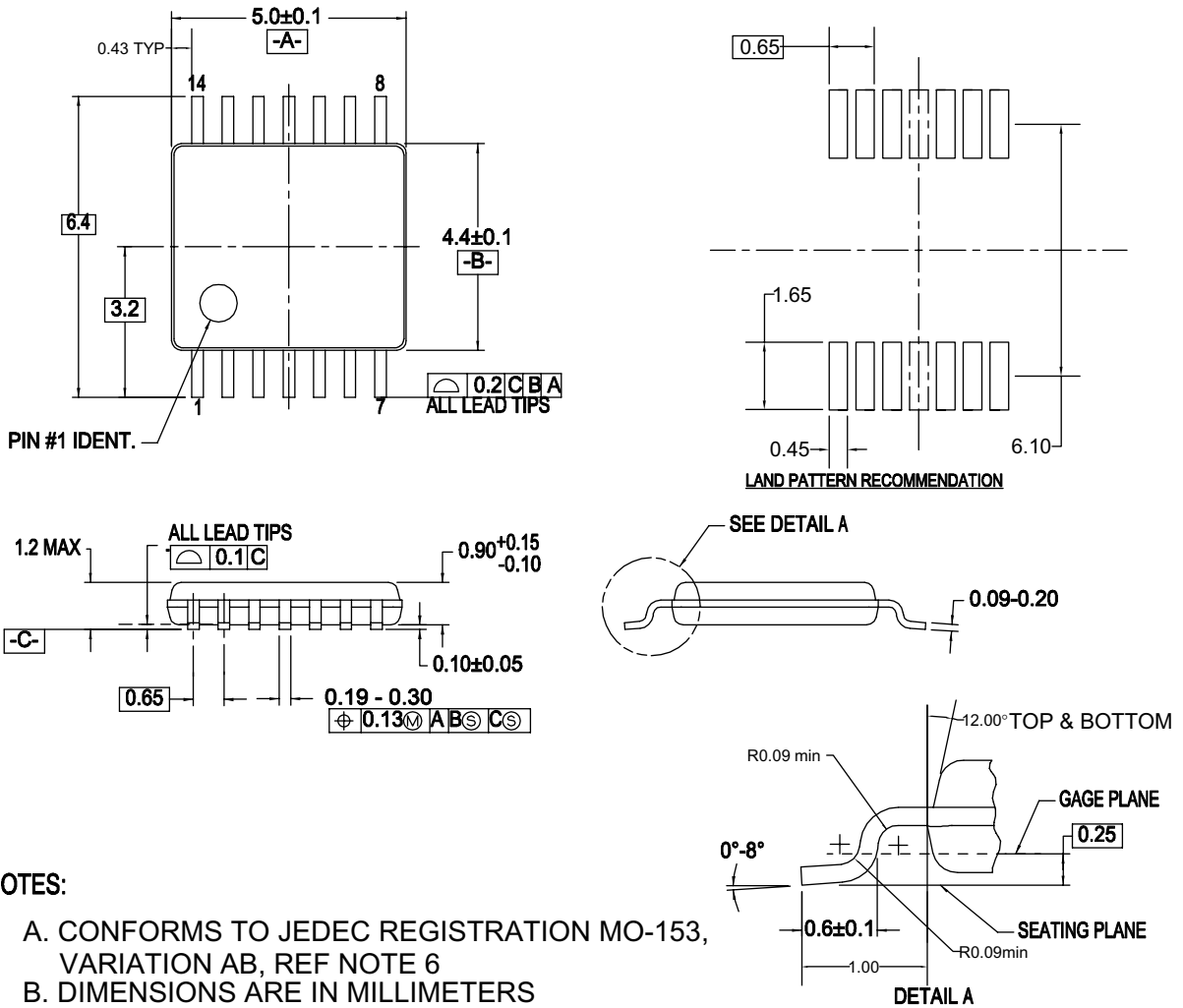
Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Physical Dimensions (Continued)



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.



Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|---|------------------------|----------------------------|----------------------|
| ACEx® | FPS™ | PDP-SPM™ | SupreMOS™ |
| Build it Now™ | FRFET® | Power220® | SyncFET™ |
| CorePLUS™ | Global Power Resource™ | POWEREDGE® | SYSTEM GENERAL® |
| CROSSVOLT™ | Green FPS™ | Power-SPM™ | The Power Franchise® |
| CTL™ | Green FPS™ e-Series™ | PowerTrench® | power franchise™ |
| Current Transfer Logic™ | GTO™ | Programmable Active Droop™ | TinyBoost™ |
| EcoSPARK® | i-Lo™ | QFET® | TinyBuck™ |
| EZSWITCH™ * | IntelliMAX™ | QS™ | TinyLogic® |
|  ™ | ISOPLANAR™ | QT Optoelectronics™ | TINYOPTO™ |
|  ™ | MegaBuck™ | Quiet Series™ | TinyPower™ |
| Fairchild® | MICROCOUPLER™ | RapidConfigure™ | TinyPVM™ |
| Fairchild Semiconductor® | MicroFET™ | SMART START™ | TinyWire™ |
| FACT Quiet Series™ | MicroPak™ | SPM® | µSerDes™ |
| FACT® | MillerDrive™ | STEALTH™ | UHC® |
| FAST® | Motion-SPM™ | SuperFET™ | Ultra FRFET™ |
| FastvCore™ | OPTOLOGIC® | SuperSOT™.3 | UniFET™ |
| FlashWriter® * | OPTOPLANAR® | SuperSOT™.6 | VCS™ |
| | | SuperSOT™.8 | |

* EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. I33